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REMARKS

This Amendment is in response to the Office Action mailed on January 5, 2007. Claims 1-4 are amended. Claims 1-3 are amended editorially. Claim 4 is amended editorially and is supported, for example, in the specification on page 7, lines 11-19 and Figures 11 and 12. Claim 5 is cancelled without prejudice or disclaimer. No new matter is added. Claims 1-4 are pending.

Claim Objections:

Claim 5 is objected to as being a substantial duplicate of claim 4. Claim 5 is cancelled without prejudice or disclaimer. Thus, Applicant respectfully requests withdrawal of this objection. Applicant does not concede the correctness of this objection.

102(e) Rejections:

Claims 4 and 5 are rejected as anticipated by Mitsui, et al. (US Patent No. 6,430,033). This rejection is traversed.

Claim 4 is directed to a solid electrolytic capacitor that requires, among other features, a capacitor element including a porous anode chip body which is a sintered body of valve-acting metal powder and a dielectric film formed on the anode chip body other than a one end surface thereof from which no anode wire projects. The solid electrolytic capacitor also requires an anode-side terminal electrically connected to the metal powder exposed on said one end surface of said anode chip body. An advantage of claim 4 is that the absence of an anode wire effectively increases the volume of the porous anode chip body, which results in a corresponding increase in the capacity of the capacitor (see page 7, lines 11-28).

Mitsui does not disclose or suggest these features. In particular, nowhere does Mitsui disclose the feature of a dielectric film formed on the anode chip body other than a one end surface thereof from which no anode wire projects. Mitsui is directed to a solid electrolytic capacitor that requires a capacitor element (2) with a sintered chip body (4) and an anode lead (3) extending from the capacitor element (2). Nowhere does Mitsui disclose a capacitor element (2) without an anode lead (3).

Furthermore, Mitsui provides no suggestion of a solid electrolytic capacitor in which the capacitor element (2) does not have an anode lead (3). Mitsui provides an oxide dielectric layer (5) that is formed along the surface of the tantalum sintered chip body (4) (see column 5, lines 48 and Figure 2). While forming the oxide dielectric layer (5), all surfaces of the sintered chip body (4) must be wetted by a chemical solution as a result of the capillary action of the process for forming an oxide dielectric layer (see column 4, lines 51-67). Thus, an anode wire (3) that is partially embedded into the capacitor element (2) is needed in Mitsui to facilitate an electrical path between an outside anode terminal plate (11) and anode metal particles inside the capacitor element (2). For at least these reasons claim 4 is not suggested by Mitsui and should be allowed.

Conclusion:

Applicant respectfully asserts claims 1-4 are in condition for allowance. If a telephone conference would be helpful in resolving any issues concerning this communication, please contact Applicant's primary attorney-of record, Douglas P. Mueller (Reg. No. 30,300), at (612) 455-3804.

Respectfully submitted,

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